



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-09-16
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7BVP*166FBM1	A	SH1A	2013-09-16
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2,15.5,4.5	3	Through-hole	
Comment	TO 220 NI CLIP;			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7BVP*166FBM1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	10.059	mg	supplier	die	Silicon (Si)	7440-21-3		8.944	mg	889154	4707
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.114	mg	11333	60
die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.025	mg	2485	13
die (s)				supplier	passivation	Alumina	1344-28-1		0.072	mg	7158	38
die (s)				supplier	passivation	Lead silicate Glass	65997-18-4	7c-I-Electrical and	0.65	mg	64619	342
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.011	mg	1094	6
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.243	mg	24157	128
Leadframe	Copper & its alloys	199.913	mg	supplier	alloy	Copper (Cu)	7440-50-8		199.713	mg	999000	105112
Leadframe				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.2	mg	1000	105
Soft solder	Solder	6.877	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.361	mg	924967	3348
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.344	mg	50022	181
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.172	mg	25011	91
Bonding wire	Other inorganic materials	35.509	mg	supplier	wire	Copper (Cu)	7440-50-8		35.509	mg	1000000	18689
encapsulation	Other Organic Materials	1641.328	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1217.865	mg	742000	640982
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		82.066	mg	50000	43193
encapsulation				supplier	mold compound	Carbon black	1333-86-4		13.131	mg	8000	6911
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		180.546	mg	110000	95024
encapsulation				supplier	mold compound	Others	Proprietary		147.72	mg	90000	77747
connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3323